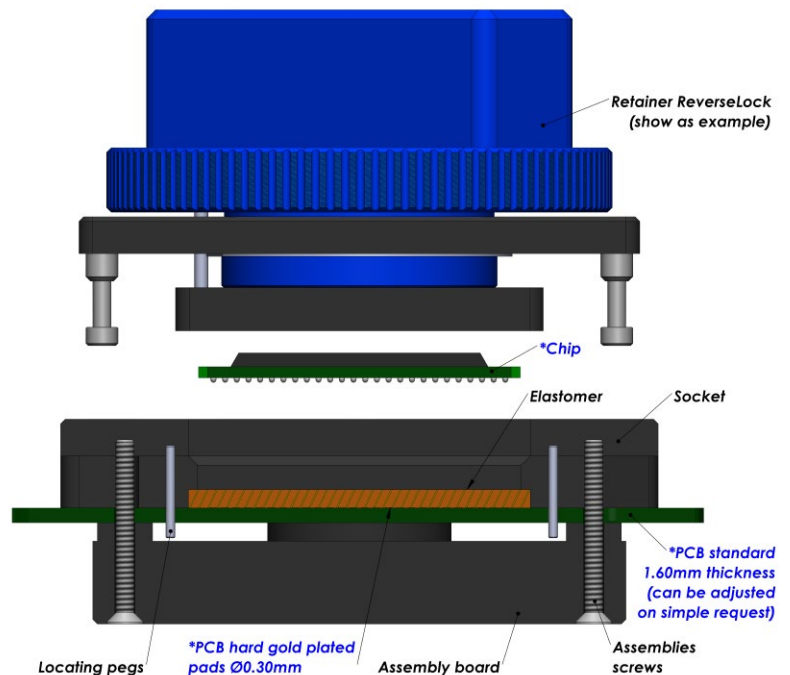
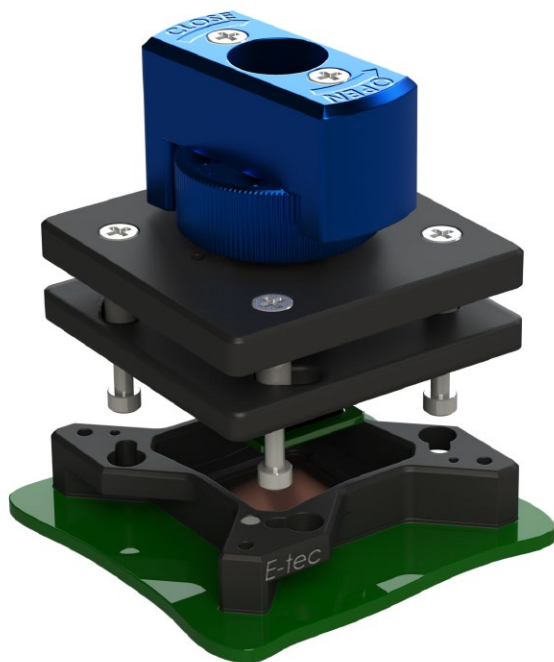
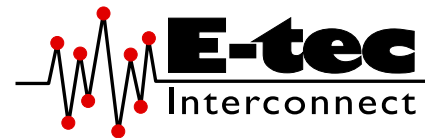


Elastomer Solderless Compression Test Socket

For BGA / Bumped chip / WLCSP / eMMC Package e

0.50 mm pitch (from 0.50mm to 0.79mm)



E-tec Interconnect AG is the world leading Test socket manufacturer

The Elastomer Solderless compression Test Sockets are ideal technical solution for good signal integrity with low signal loss. The sockets are available for any chip size and pitch and are attached with 2, 4 or 8 screws to the PCB. The socket outline will be kept to a minimum and special clearances can be offered to avoid components on the PCB.

SMT and thru-hole adapter sockets are available in certain pitches (contact factory for availability first) with these elastomer interposers to allow using this high frequency interposer on PCB's which have already been laid out for SMT or thru-hole sockets. We aim to solve your requirements. Please note, we will always request the chip data to ensure we offer a compatible socket.

| Contacts Specifications | | | |
|-------------------------|-----------------|------------|------------|
| Contact type code | E1 | E2 | E3 |
| Application | High Frequency | | |
| Mounting | Solderless | Solderless | Solderless |
| Bandwidth (GHz@-1dB) | 17 GHz | 34 GHz | >40 GHz |
| Contact resistance | 30 mOhm | | |
| Chip contact tip shape | Gold Wire | | |
| PCB tip shape | Gold Wire | | |
| Force | 20 gr to 50 gr | | |
| Current rating | 2.5 A | | |
| Capacitance pF | 0.14 pF | 0.10 pF | 0.06 pF |
| Inductance nH | 0.23 nH | 0.30 nH | 0.03 nH |
| Impedance Ohms | 41.3 Ω | 47.1 Ω | 51.1 Ω |
| Temperature range | -40°C to +125°C | | |
| Mating cycles | 1 K | | |

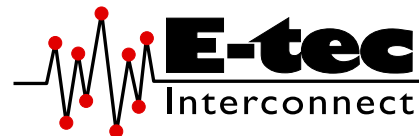
More on the next page



Elastomer Solderless Compression Test Socket

For BGA / Bumped chip / WLCSP / eMMC Package e

0.50 mm pitch (from 0.50mm to 0.79mm)

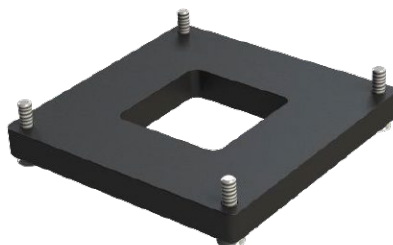


Standard assembly boards

Small Chip size



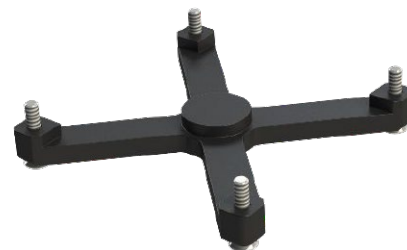
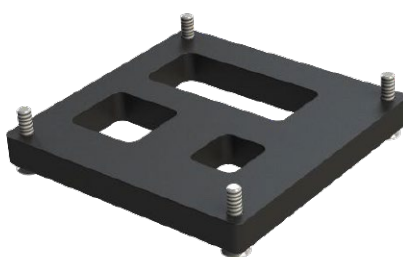
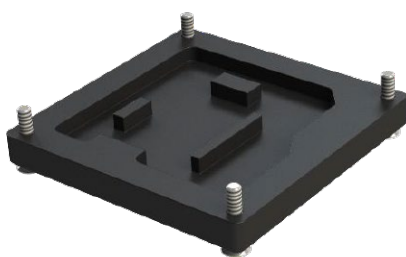
Medium Chip size



Large Chip size



Custom assembly boards



How to order

BE# #### -05E# - ##### 55L #

Shape of tip

E : Elastomer

Nbr of contacts

Depends on ballcount of chip

Contact type

E1 : High Frequency 17 GHz
E2 : High Frequency 34 GHz
E3 : High Frequency 40 GHz

Plating

55L: Gold + Locating pegs

Option code (see page 16-19)

M : Multi frames
U : Multi packages
S : Custom opening slot
H : Heatsink
F : Fan + Heatsink
W : Transparent lid
I : Steel retention lid
B : Aluminium retention lid
G : Handling button

Retention frame type (Lid) (see page 12-15)

W: TwistLock
F : FastLock
B : SpringLock
H : Open Clamshell Alu (<200 contacts)
J : Clamshell Alu (>200 contacts)
L : Open Lever Clamshell Alu (>200 contacts)
S : ScrewLock
Q : Open QuickLock (<200 contacts)
D : QuickLock (>200 contacts)
M : Injection Molded ClamShell
R : ReverseLock
T : SlimLock

Grid code / Config. code

Will be given by the factory after receipt of the chip datasheet

